

Light on a chip - more complex concepts

# Hetero- or hybrid PIC, light switching and control, non-linear optical materials

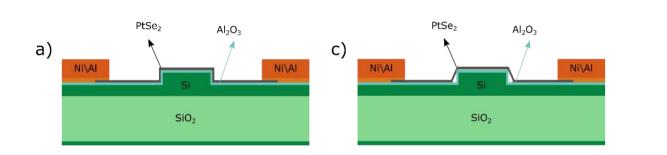


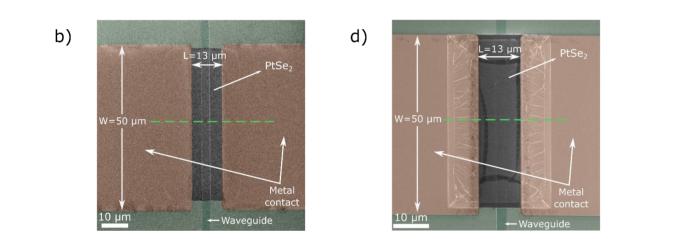
- Large number of required functions "on-the-chip": photon sources, modulators, frequency converters, detectors, electronic control elements, ...
- "On the chip": coupling losses between the components are eliminated,
- Complex structures  $\rightarrow$  "photonic integrated circuits" (PICs)
- Not all functions can be realized in one material  $\rightarrow$  Hybrid integration

#### Hetero and hybrid PICs 2

#### Integration of 2D materials

- Almost independent of substrate
- Example: Topography-compliant deposition of platinum diselenide (PtSe<sub>2</sub>) on SOI waveguides, e.g. as a photodetector, as a heating element

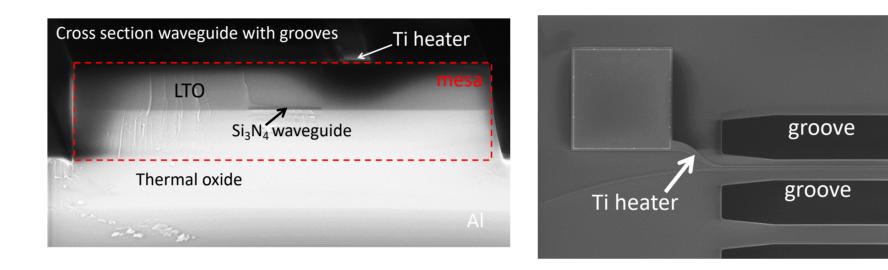




#### Switching & controlling light 3

#### **Thermo-optical switches**

- Simple production, independent of substrate
- Heating wire made of metal or transparent 2D material (e.g. graphene,  $PtSe_2$ ,  $MoS_2$ )



(left) Cross-section of a Si<sub>3</sub>N<sub>4</sub> waveguide with Ti heating element and trenches for thermal insulation, (right) top view.

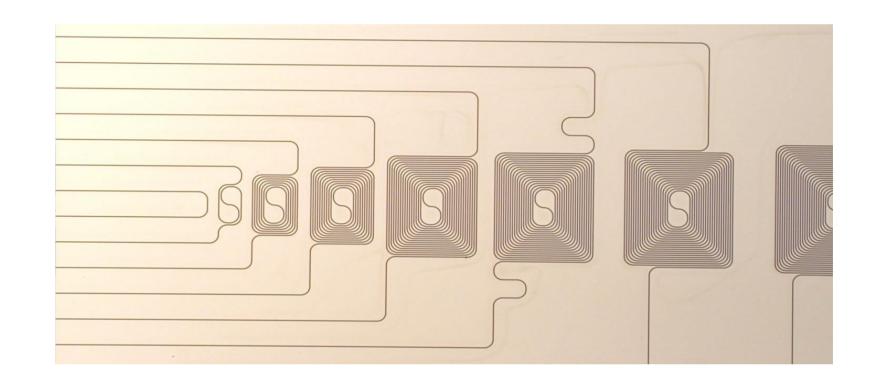
# Aluminum nitride AIN

4

- Waveguide material with  $\chi^{(2)}$
- C-axis-oriented growth, e.g. sputtered on sapphire or SiO<sub>2</sub>

**Nonlinear-optical materials** 

Transparency range: UV-C to IR



PtSe<sub>2</sub> on SOI waveguides, e.g. as a photodetector: topography-conformal deposition (a,b) or by means of transfer with typical defects (c,d).

#### Hybrid chip-to-chip integration

- Optimal combination of active and passive material systems
- Yield management through the use of "known good dies"



Complex hybrid PIC based on  $Si_3N_4$ , InP and polymer

#### **Integration of GaAs-based lasers**

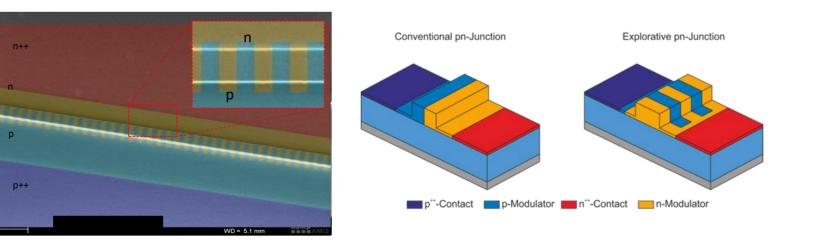
- Wavelength range: 630 nm 1180 nm
- Micro-transfer printing of GaAs chiplets on photonic integrated circuits

For "hybrid integration" see also poster QC08

"Scalable assembly and connection technology"

# Electro-optical charge carrier-based switches

- Injection or depletion type
- Available in SOI or InP
- Fast and energy-efficient, but more complex production than thermo-optical



(left) False color SEM of a depletion modulator: SOI waveguide with interdigitated implantation regions, (right) modulator schematic.

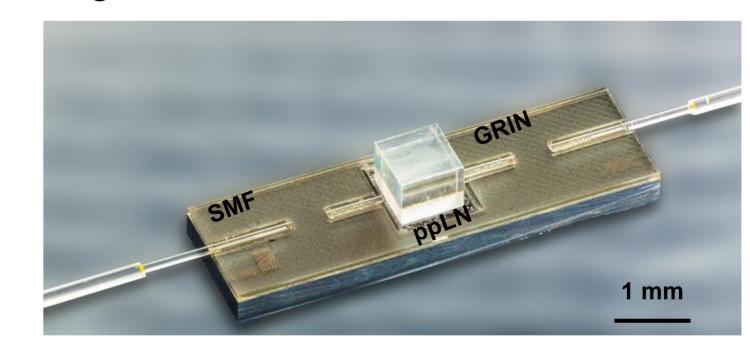
## Electro-optical $\chi^{(2)}$ -based switching

- Switching and fast modulation via electric field strength
- Available in LNOI and InP

AIN waveguide with **0.13 dB/cm** loss at 1550 nm

## **PIC** integration of crystals

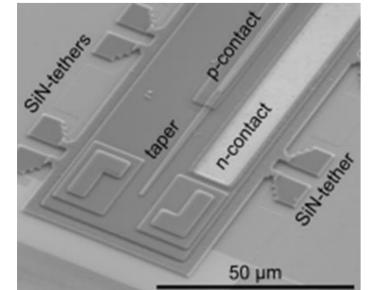
Integration of classical nonlinear crystals (ppLN, ppKTP, ...) into on-chip free beam regions



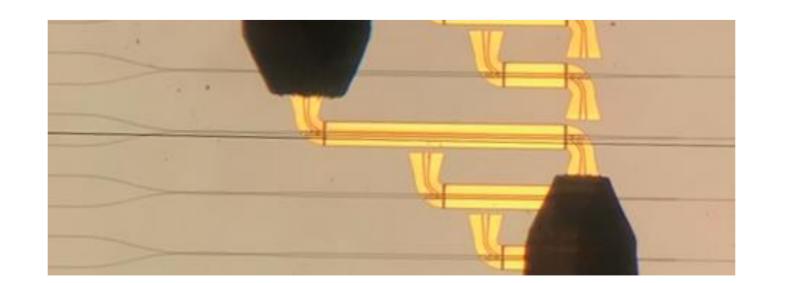
PIC with PPLN crystal for SHG and SPDC

# **Barium magnesium fluoride BaMgF**<sub>4</sub>

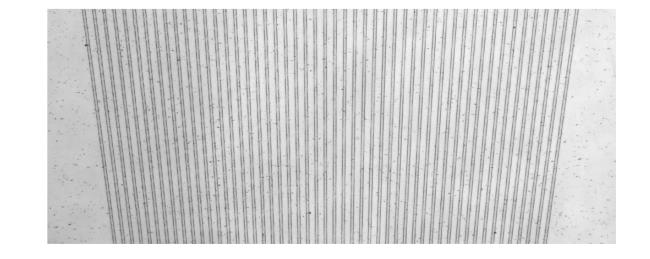
- Ultra-wide transparency range
- Quasi-phase matching for frequency conversion across the transparency range possible



SEM image of a transferprintable evanescently coupled amplifier chiplet emitting around 950 nm



#### High-frequency modulator in LNOI



Periodically poled fan-out structure in BaMgF<sub>4</sub> produced by maskless poling

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